



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

<b>Supplier Information</b>			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	28-11-2023
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Material Declaration champion	<b>Representative Title</b>	Material Declaration champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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<b>Legal Statement</b>			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32U535RCT6Q	785W*455XXXY	A	998Z	28-11-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	363.53	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10	64	L bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-14th June 2023				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	785W*45XXXX				6000000.0	1000004.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	10.137	mg	Supplier	die	Silicon (Si)	7440-21-3		9.741	mg	960935	26796
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.044	mg	4341	121
				Supplier	metallization	Copper (Cu)	7440-50-8		0.130	mg	12824	358
				Supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	99	3
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.022	mg	2170	61
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	592	17
				Supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	99	3
				Supplier	Passivation	Silicon Nitride	12033-89-5		0.031	mg	3058	85
Glue Epoxy (3230)	M-011 Other inorganic materials	1.379	mg	Supplier	Passivation	Silicon Oxide	7631-86-9		0.161	mg	15882	443
				Supplier	Metals	Silver	7440-22-4		1.124	mg	815000	3092
				Supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))	39817-09-9		0.041	mg	30000	114
				Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.041	mg	30000	114
				Supplier	Organic Compounds	Epoxy resin	Proprietary		0.041	mg	30000	114
				Supplier	Organic Compounds	Dodecylloxirane	3234-28-4		0.041	mg	30000	114
				Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.041	mg	30000	114
				Supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.041	mg	30000	114
Mold Compound (EME-G631SHQ)	M-011 Other inorganic materials	245.001	mg	Supplier	Metallic compounds	Copper oxide	1317-38-0		0.007	mg	5000	19
				Supplier	Plastics/polymers	Epoxy Resin A	Trade Secret		5.145	mg	21000	14153
				Supplier	Plastics/polymers	Epoxy Resin B	Trade Secret		5.145	mg	21000	14153
				Supplier	Plastics/polymers	Phenol Resin	Trade Secret		13.720	mg	56000	37742
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		191.211	mg	780450	525989
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		28.254	mg	115320	77721
				Supplier	Non-metals	Carbon Black	1333-86-4		1.526	mg	6230	4199
				Supplier	Metals	Gold	7440-57-5		1.273	mg	1000000	3501
Wire (Au)	Bonding Wire	1.273	mg	Supplier	Metals	Gold	7440-57-5		1.273	mg	1000000	3501
Plating anode (Pure Tin)	M-011 Other inorganic materials	1.438	mg	Supplier	Metals	Tin	7440-31-5		1.438	mg	1000000	3955
Leadframe (C194+Ag)	Copper & its alloys	104.300	mg	Supplier	Metals	Copper	7440-50-8		101.400	mg	972200	278935
				Supplier	Metals	Iron	7439-89-6		2.388	mg	22900	6570
				Supplier	Metals	Zinc	7440-66-6		0.156	mg	1500	430
				Supplier	Non-Metals	Phosphorus	7723-14-0		0.031	mg	300	86
				Supplier	Metals	Silver	7440-22-4		0.323	mg	3100	889